01-21-1999

100946979

**)VER SHEET** 

U.S. Department of Commerce Patent and Trademark Office

6	To the Honorable Commission 100946979	ord the attached original documents or copy thereof
d	Name of conveying party(ies):	Name and address of receiving party(ies):
8	Cem Basceri	Name: Micron Technology, Inc. စု
-1 F	Additional name(s) of conveying  party(ies) attached?  X	Name: Micron Technology, Inc.  Internal Address: 8000 S. Federal Way Boise, Idaho 83706-9632
Z	. 77 /	Street Address: 8000 S. Federal Way Boise, Idaho 83706-9632
W	3. Nature of Conveyance:	יים
	X Assignment Merger	City: Boise
	Security Agreement Change of Name Other	Country: U.S.A. Zip: 83706-9632
	Execution Date: _January 5, 1999	Additional names(s) & Yes address(es) attached? x No
	Application number(s) or patent number(s):  If this document is being filed together with a new application,	the execution date(s) of the application is January 5, 1999
	A. Patent Application No.(s):	B. Patent No.(s):
	09 228293	Additional numbers attached? Yes X No
	<ol><li>Name and address of party whom correspondence concerning document should be mailed:</li></ol>	6. Total number of applications and patents involved: 1
	Name: DICKSTEIN SHAPIRO MORIN & OSHIINSKY LLP	7. Total fee (37 CFR 3.41) \$ 40.00
	Internal Address: Atty. Dkt.: M4065.139/P139	X Enclosed
	Attn: Thomas J. D'Amico	Authorized to be charged to deposit account
	Street Address: 2101 L Street NW	
	City: Washington State: DC Zip: 20037-1526	8. Deposit account number: 04-1073
	720/1999 DNGUYEN 00000115 09228293 FC:581 40.00 OP DO NOT USE	THIS SPACE FLC OK
· [	9. Statement and signature.	
	To the best of my knowledge and belief, the foregoin is a true copy of the original document.  Thomas J. D'Amico	g information is true and correct and any attached copy  January 8, 1999
	Signature	Date
	Reg. No. 28,371	
	Total number of pages including cover sheet, attachr	ments, and document: 3

**PATENT REEL: 9701 FRAME: 0950** 

Docket No.: M4065.139 Micron No.: 98-0981.00/US

## ASSIGNMENT AND AGREEMENT

For value received, I, Cem Basceri of Boise, Idaho, hereby sell, assign and transfer to Micron Technology Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled METHOD FOR IMPROVING THE SIDEWALL STOICHIOMETRY OF THIN FILM CAPACITORS described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United State for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

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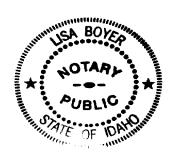
PATENT REEL: 9701 FRAME: 0951

Docket No.: M4065.139 Micron No.: 98-0981.00/US

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

United States of America ) State of <u>Idaho</u> )ss.: County of <u>Ada</u> )

On this 5 day of anuary, 1998, before me personally came Cem Basceri, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.



**RECORDED: 01/08/1999** 

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**PATENT REEL: 9701 FRAME: 0952**